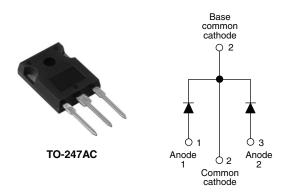


Vishay High Power Products

HEXFRED® Ultrafast Soft Recovery Diode, 2 x 16 A



PRODUCT SUMMARY					
V _R per leg	1200 V				
V _F at 16 A at 25 °C	3.0 V				
I _{F(AV)}	2 x 16 A				
t _{rr} (typical) per leg	30 ns				
T _J (maximum)	150 °C				
Q _{rr} (typical) per leg	260 nC				
I _{RRM} (typical) per leg	5.8 A				

FEATURES

- · Ultrafast recovery
- · Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- · Specified at operating conditions
- · Lead (Pb)-free
- · Designed and qualified for industrial level

Pb-free Available



BENEFITS

- · Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- · Higher frequency operation
- Reduced snubbing
- · Reduced parts count

DESCRIPTION

HFA32PA120C is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 16 A per leg continuous current, the HFA32PA120C is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the th portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA32PA120C is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL TEST CONDITIONS		VALUES	UNITS	
Cathode to anode voltage	V _R		1200	V	
Maximum continuous forward current	- I _F	T _C = 100 °C	16		
per device			32	Α	
Single pulse forward current	I _{FSM}		190	A	
Maximum repetitive forward current	I _{FRM}		64		
Maximum navor discination	P _D	T _C = 25 °C	151	°C	
Maximum power dissipation		T _C = 100 °C	60	• •	
Operating junction and storage temperature range	T _J , T _{Stg}		- 55 to + 150	W	

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

HFA32PA120CPbF

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ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	Ι _R = 100 μΑ		1200	-	-	
		I _F = 16 A		-	2.5	3.0	V
Maximum forward voltage V _{FM}	V_{FM}	I _F = 32 A	See fig. 1	-	3.2	3.93	
		I _F = 16 A, T _J = 125 °C		-	2.3	2.7	
Maximum reverse		$V_R = V_R$ rated	See fig. 2	-	0.75	20	
leakage current	I _{RM}	$T_J = 125 ^{\circ}\text{C}, V_R = 0.8 \text{x} V_R \text{rated}$	See lig. 2	-	375	2000	μΑ
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	27	40	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	8.0	-	nΗ

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	30	-	
Reverse recovery time See fig. 5, 10	t _{rr1}	T _J = 25 °C	-	90	135	ns	
300 lig. 0, 10	t _{rr2}	T _J = 125 °C		-	164	245	
Peak recovery current	I _{RRM1}	T _J = 25 °C	$I_F = 16 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	5.8	10	А
See fig. 6	I _{RRM2}	T _J = 125 °C		-	8.3	15	
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	260	675	nC
See fig. 7	Q _{rr2}	T _J = 125 °C		-	680	1838	110
Peak rate of fall of recovery	dI _{(rec)M} /dt1	T _J = 25 °C		-	120	-	A/μs
current during t _b See fig. 8	dI _{(rec)M} /dt2	T _J = 125 °C		-	76	-	Ανμδ

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	-	0.83	
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	K/W
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.50	-	
Majaht			-	2.0	-	g
Weight			-	0.07	-	OZ.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC (JEDEC)	HFA32PA120C		•	

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HEXFRED® Vishay High Power Products Ultrafast Soft Recovery Diode, 2 x 16 A

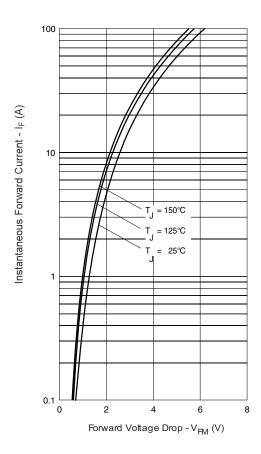


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

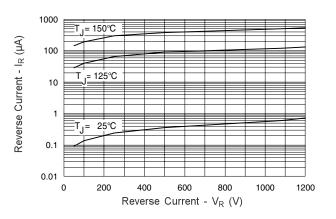


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

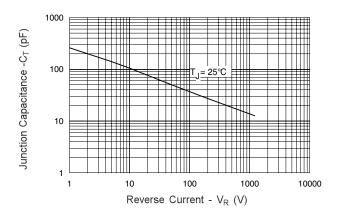


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

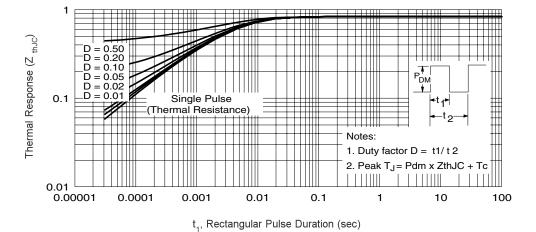


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

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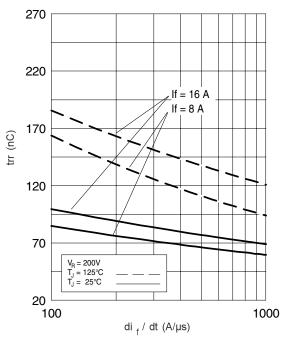


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt (Per Leg)

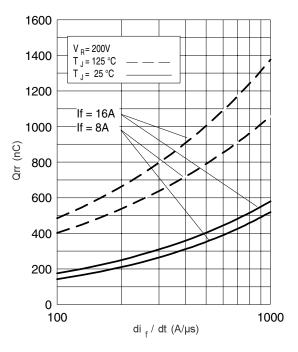


Fig. 7 - Typical Stored Charge vs. dI_F/dt (Per Leg)

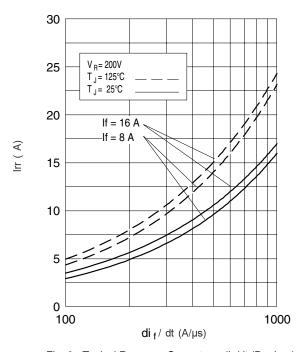


Fig. 6 - Typical Recovery Current vs. dI_F/dt (Per Leg)

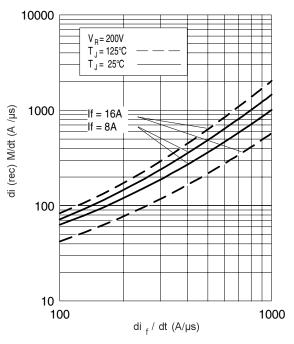


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)



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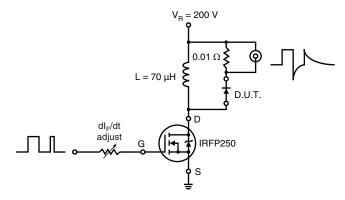
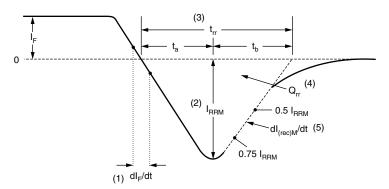


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- $\begin{array}{l} \text{(3) } \textbf{t}_{\text{rr}} \text{ reverse recovery time measured} \\ \text{from zero crossing point of negative} \\ \text{going I}_{\text{F}} \text{ to point where a line passing} \\ \text{through 0.75 I}_{\text{RRM}} \text{ and 0.50 I}_{\text{RRM}} \\ \text{extrapolated to zero current.} \end{array}$
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

HFA32PA120CPbF

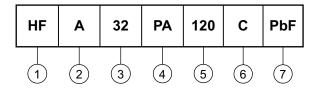
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ORDERING INFORMATION TABLE

Device code



- 1 HEXFRED® family
- 2 Process designator: A = Subs. electron irradiated

B = Subs. platinum

- 3 Current rating (32 = 32 A)
- 4 Package outline (PA = TO-247, 3 pins)
- 5 Voltage rating (120 = 1200 V)
- 6 Configuration (C = Center tap common cathode)
- 7 • None = Standard production
 - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS				
Dimensions http://www.vishay.com/doc?95223				
Part marking information	http://www.vishay.com/doc?95226			

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